

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (original): A method, comprising:

applying photo-thermal energy to a layer of first material disposed on a layer of second material to diffuse a portion of the first material into the second material.

Claim 2 (original): The method of claim 1, wherein:

the photo-thermal energy is provided by one of a YAG laser, a CO₂ laser, and an infrared laser.

Claim 3 (amended): The method of claim 1 wherein:

the second material includes metal; and

the photo-thermal energy penetrates at least into the first layer layer of first material such that the diffusing forms an electrically conductive trace.

Claim 4 (amended): The method of claim 3, wherein:

the first material includes tin, the second material includes copper, and the metal trace electrically conductive trace includes a copper tin alloy.

Claim 5 (original): The method of claim 3, wherein:

the photo-thermal energy includes a laser beam having a width between about 2 mils and about 8 mils.

Claims 6-10 (cancelled)

Claim 11 (original): A method comprising:

forming a metal layer on a core;
placing a diffusion layer on the metal layer; and
applying photo-thermal energy to the diffusion layer to diffuse a portion of the diffusion layer into the metal layer.

Claims 12-26 (cancelled)

Claim 27 (new): The method of claim 1, wherein:

the first material comprises a bottom surface and the first material diffuses into the second material such that an alloy is formed below the bottom surface of the first material.

Claim 28 (new): The method of claim 1, wherein:

the photo-thermal energy causes the first material and the second material to ablate into a plasma.

Claim 29 (new): The method of claim 1, wherein:

the photo-thermal energy is provided by a laser programmed to pattern a desired pattern of electrically conductive traces.

Claim 30 (new): The method of claim 3, further comprising:

removing non-diffused portions of the layer of first material.